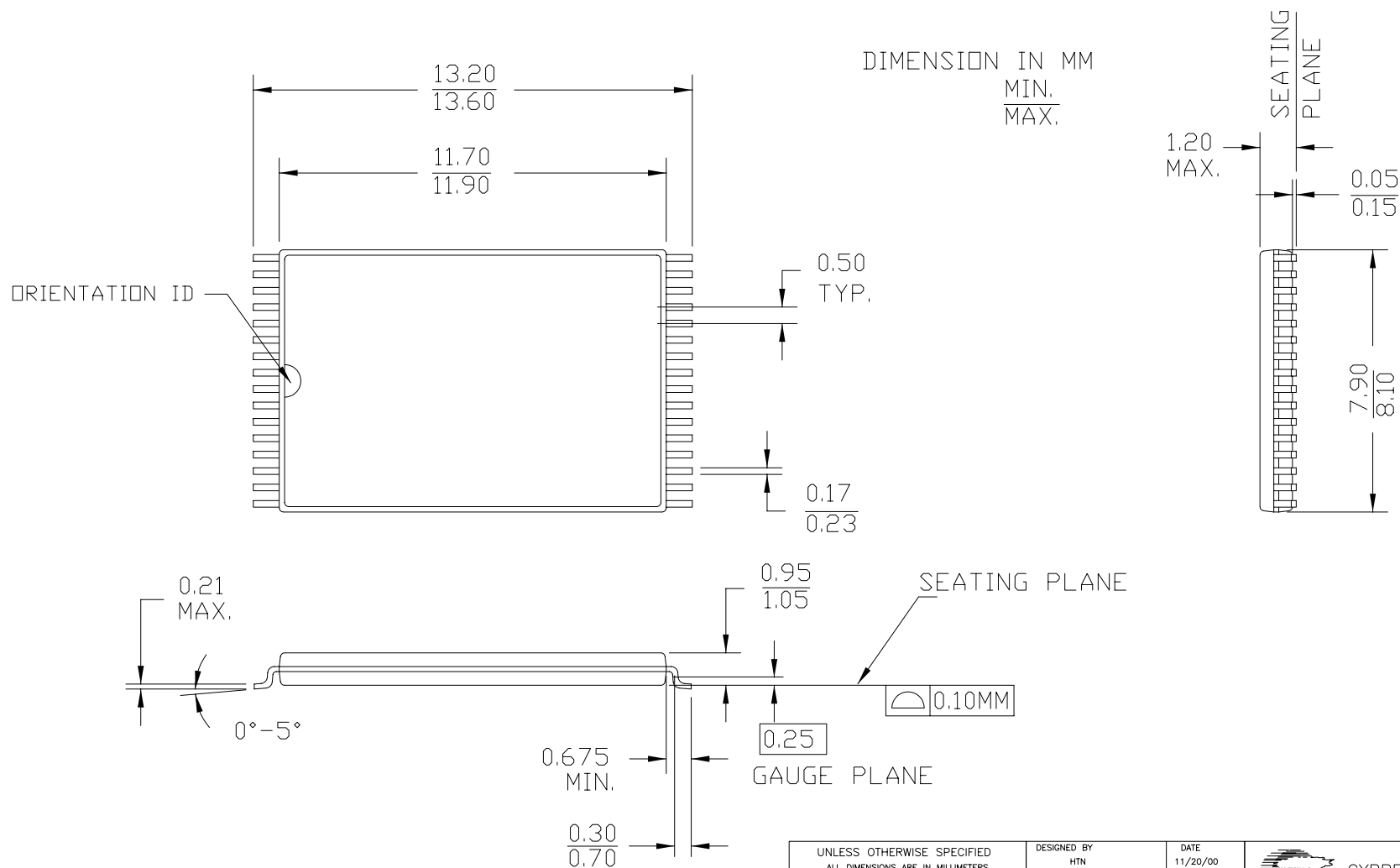



32 Lead TSOP 8 X 13.4 mm STANDARD

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	50588	NEW RELEASE	06/11/97	N/A
1	-	*A	58835	CHG. LEAD THICKNESS DIM.	09/28/98	N/A
1	-	*B	66396	REMOVE THE INCH UNIT ON DIMENSIONS	02/18/00	N/A
1	-	*C	102262	REMOVE PIN NUMBERS	09/26/00	N/A
1	-	*D	103908	CHG. PIN 1 ORIENTATION TO ORIENTATION ID	11/20/00	N/A
1	-	*E	2866234	Changed Template and Title from 32LD SMALL TSOP PKG. OUTL. to PACKAGE OUTLINE, 32LD SMALL TSOP 8X13.4X1.2 MM ZA32.	01/26/10	QAD

DIMENSION IN MM
MIN.
MAX.



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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY HTN	DATE 11/20/00	 CYPRESS Company Confidential	
	DRAWN BY HTN	DATE 11/20/00		
	CHECKED BY TSV	DATE 01/26/10		
	APPROVED BY QAD	DATE 01/26/10		
MATERIAL N/A	APPROVED BY JGUA	DATE 01/26/10	TITLE PACKAGE OUTLINE, 32LD SMALL TSOP 8X13.4X1.2 MM ZA32	
FINISH N/A	APPROVED BY N/A	DATE N/A	SIZE A	PART NO. ZA32
			DWG NO 51-85094	REV *E
			SCALED TO FIT N/A	SHEET 1 OF 1